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Intel - EP20K200RC208-1V Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	832
Number of Logic Elements/Cells	8320
Total RAM Bits	106496
Number of I/O	144
Number of Gates	526000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP Exposed Pad
Supplier Device Package	208-RQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k200rc208-1v

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General Description

APEX[™] 20K devices are the first PLDs designed with the MultiCore architecture, which combines the strengths of LUT-based and productterm-based devices with an enhanced memory structure. LUT-based logic provides optimized performance and efficiency for data-path, registerintensive, mathematical, or digital signal processing (DSP) designs. Product-term-based logic is optimized for complex combinatorial paths, such as complex state machines. LUT- and product-term-based logic combined with memory functions and a wide variety of MegaCore and AMPP functions make the APEX 20K device architecture uniquely suited for system-on-a-programmable-chip designs. Applications historically requiring a combination of LUT-, product-term-, and memory-based devices can now be integrated into one APEX 20K device.

APEX 20KE devices are a superset of APEX 20K devices and include additional features such as advanced I/O standard support, CAM, additional global clocks, and enhanced ClockLock clock circuitry. In addition, APEX 20KE devices extend the APEX 20K family to 1.5 million gates. APEX 20KE devices are denoted with an "E" suffix in the device name (e.g., the EP20K1000E device is an APEX 20KE device). Table 8 compares the features included in APEX 20K and APEX 20KE devices.

Feature	APEX 20K Devices	APFX 20KF Devices
32/64-Bit, 33-MHz PCI	grades	Full compliance in -1, -2 speed grades
32/64-Bit, 66-MHz PCI	-	Full compliance in -1 speed grade
MultiVolt I/O	2.5-V or 3.3-V V _{CCIO}	1.8-V, 2.5-V, or 3.3-V V _{CCIO}
	V _{CCIO} selected for device	V _{CCIO} selected block-by-block
	Certain devices are 5.0-V tolerant	5.0-V tolerant with use of external resistor
ClockLock support	Clock delay reduction	Clock delay reduction
	2× and 4× clock multiplication	$m/(n \times v)$ or $m/(n \times k)$ clock multiplication
		Drive ClockLock output off-chip
		External clock feedback
		ClockShift
		LVDS support
		Up to four PLLs
		ClockShift, clock phase adjustment
Dedicated clock and input pins	Six	Eight
I/O standard support	2.5-V, 3.3-V, 5.0-V I/O	1.8-V, 2.5-V, 3.3-V, 5.0-V I/O
	3.3-V PCI	2.5-V I/O
	Low-voltage complementary	3.3-V PCI and PCI-X
	metal-oxide semiconductor	3.3-V Advanced Graphics Port (AGP)
	(LVCMOS)	Center tap terminated (CTT)
	Low-voltage transistor-to-transistor	GTL+
	logic (LVTTL)	LVCMOS
		True-LVDS and LVPECL data pins
		(In EP20K300E and larger devices)
		LVDS and LVPECL signaling (in all BGA
		and FineLine BGA devices)
		LVDS and LVPECL data pins up to
		156 Mbps (III - I speed grade devices)
		SSTL-3 Class Land II
Memory support	Dual-port BAM	CAM
	FIFO	Dual-port BAM
	BAM	FIFO
	BOM	BAM
		ROM

Logic Array Block

Each LAB consists of 10 LEs, the LEs' associated carry and cascade chains, LAB control signals, and the local interconnect. The local interconnect transfers signals between LEs in the same or adjacent LABs, IOEs, or ESBs. The Quartus II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of a fast local interconnect for high performance. Figure 3 shows the APEX 20K LAB.

APEX 20K devices use an interleaved LAB structure. This structure allows each LE to drive two local interconnect areas. This feature minimizes use of the MegaLAB and FastTrack interconnect, providing higher performance and flexibility. Each LE can drive 29 other LEs through the fast local interconnect.





Cascade Chain

With the cascade chain, the APEX 20K architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry.

Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. Figure 7 shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.



Figure 7. APEX 20K Cascade Chain



Figure 14. APEX 20K Macrocell

For registered functions, each macrocell register can be programmed individually to implement D, T, JK, or SR operation with programmable clock control. The register can be bypassed for combinatorial operation. During design entry, the designer specifies the desired register type; the Quartus II software then selects the most efficient register operation for each registered function to optimize resource utilization. The Quartus II software or other synthesis tools can also select the most efficient register operation automatically when synthesizing HDL designs.

Each programmable register can be clocked by one of two ESB-wide clocks. The ESB-wide clocks can be generated from device dedicated clock pins, global signals, or local interconnect. Each clock also has an associated clock enable, generated from the local interconnect. The clock and clock enable signals are related for a particular ESB; any macrocell using a clock also uses the associated clock enable.

If both the rising and falling edges of a clock are used in an ESB, both ESB-wide clock signals are used.





Embedded System Block

The ESB can implement various types of memory blocks, including dual-port RAM, ROM, FIFO, and CAM blocks. The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a dual-port mode, which supports simultaneous reads and writes at two different clock frequencies. Figure 17 shows the ESB block diagram.





Input/Output Clock Mode

The input/output clock mode contains two clocks. One clock controls all registers for inputs into the ESB: data input, WE, RE, read address, and write address. The other clock controls the ESB data output registers. The ESB also supports clock enable and asynchronous clear signals; these signals also control the reading and writing of registers independently. Input/output clock mode is commonly used for applications where the reads and writes occur at the same system frequency, but require different clock enable signals for the input and output registers. Figure 21 shows the ESB in input/output clock mode.



Figure 21. ESB in Input/Output Clock Mode

Notes to Figure 21:

All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset. (1)APEX 20KE devices have four dedicated clocks. (2)

Single-Port Mode

The APEX 20K ESB also supports a single-port mode, which is used when simultaneous reads and writes are not required. See Figure 22.

Altera Corporation



Figure 23. APEX 20KE CAM Block Diagram

CAM can be used in any application requiring high-speed searches, such as networking, communications, data compression, and cache management.

The APEX 20KE on-chip CAM provides faster system performance than traditional discrete CAM. Integrating CAM and logic into the APEX 20KE device eliminates off-chip and on-chip delays, improving system performance.

When in CAM mode, the ESB implements 32-word, 32-bit CAM. Wider or deeper CAM can be implemented by combining multiple CAMs with some ancillary logic implemented in LEs. The Quartus II software combines ESBs and LEs automatically to create larger CAMs.

CAM supports writing "don't care" bits into words of the memory. The "don't-care" bit can be used as a mask for CAM comparisons; any bit set to "don't-care" has no effect on matches.

The output of the CAM can be encoded or unencoded. When encoded, the ESB outputs an encoded address of the data's location. For instance, if the data is located in address 12, the ESB output is 12. When unencoded, the ESB uses its 16 outputs to show the location of the data over two clock cycles. In this case, if the data is located in address 12, the 12th output line goes high. When using unencoded outputs, two clock cycles are required to read the output because a 16-bit output bus is used to show the status of 32 words.

The encoded output is better suited for designs that ensure duplicate data is not written into the CAM. If duplicate data is written into two locations, the CAM's output will be incorrect. If the CAM may contain duplicate data, the unencoded output is a better solution; CAM with unencoded outputs can distinguish multiple data locations.

CAM can be pre-loaded with data during configuration, or it can be written during system operation. In most cases, two clock cycles are required to write each word into CAM. When "don't-care" bits are used, a third clock cycle is required.

Figure 26. APEX 20KE Bidirectional I/O Registers N





Notes to Figure 26:

- (1) This programmable delay has four settings: off and three levels of delay.
- (2) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Clock Phase & Delay Adjustment

The APEX 20KE ClockShift feature allows the clock phase and delay to be adjusted. The clock phase can be adjusted by 90° steps. The clock delay can be adjusted to increase or decrease the clock delay by an arbitrary amount, up to one clock period.

LVDS Support

Two PLLs are designed to support the LVDS interface. When using LVDS, the I/O clock runs at a slower rate than the data transfer rate. Thus, PLLs are used to multiply the I/O clock internally to capture the LVDS data. For example, an I/O clock may run at 105 MHz to support 840 megabits per second (Mbps) LVDS data transfer. In this example, the PLL multiplies the incoming clock by eight to support the high-speed data transfer. You can use PLLs in EP20K400E and larger devices for high-speed LVDS interfacing.

Lock Signals

The APEX 20KE ClockLock circuitry supports individual LOCK signals. The LOCK signal drives high when the ClockLock circuit has locked onto the input clock. The LOCK signals are optional for each ClockLock circuit; when not used, they are I/O pins.

ClockLock & ClockBoost Timing Parameters

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the APEX 20K ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. In APEX 20KE devices, the clock input standard is programmable, so the PLL cannot respond to the clock until the device is configured. The PLL locks onto the input clock as soon as configuration is complete. Figure 30 shows the incoming and generated clock specifications.

For more information on ClockLock and ClockBoost circuitry, see Application Note 115: Using the ClockLock and ClockBoost PLL Features in APEX Devices.

Table 15. APEX 20K ClockLock & ClockBoost Parameters for -1 Speed-Grade Devices (Part 2 of 2)										
Symbol	Parameter	Min	Max	Unit						
t _{SKEW}	Skew delay between related ClockLock/ClockBoost-generated clocks		500	ps						
t _{JITTER}	Jitter on ClockLock/ClockBoost-generated clock (5)		200	ps						
t _{INCLKSTB}	Input clock stability (measured between adjacent clocks)		50	ps						

Notes to Table 15:

- (1) The PLL input frequency range for the EP20K100-1X device for 1x multiplication is 25 MHz to 175 MHz.
- (2) All input clock specifications must be met. The PLL may not lock onto an incoming clock if the clock specifications are not met, creating an erroneous clock within the device.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured first. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration, because the lock time is less than the configuration time.
- (4) The jitter specification is measured under long-term observation.
- (5) If the input clock stability is 100 ps, t_{JITTER} is 250 ps.

Table 16 summarizes the APEX 20K ClockLock and ClockBoost parameters for -2 speed grade devices.

Symbol	Parameter	Min	Max	Unit
f _{OUT}	Output frequency	25	170	MHz
f _{CLK1}	Input clock frequency (ClockBoost clock multiplication factor equals 1)	25	170	MHz
f _{CLK2}	Input clock frequency (ClockBoost clock multiplication factor equals 2)	16	80	MHz
f _{CLK4}	Input clock frequency (ClockBoost clock multiplication factor equals 4)	10	34	MHz
t _{OUTDUTY}	Duty cycle for ClockLock/ClockBoost-generated clock	40	60	%
f _{CLKDEV}	Input deviation from user specification in the Quartus II software (ClockBoost clock multiplication factor equals one) (1)		25,000 (2)	PPM
t _R	Input rise time		5	ns
t _F	Input fall time		5	ns
t _{LOCK}	Time required for ClockLock/ ClockBoost to acquire lock (3)		10	μs
t _{SKEW}	Skew delay between related ClockLock/ ClockBoost- generated clock	500	500	ps
t _{JITTER}	Jitter on ClockLock/ ClockBoost-generated clock (4)		200	ps
t _{INCLKSTB}	Input clock stability (measured between adjacent clocks)		50	ps

Table 16. APEX 20K ClockLock & ClockBoost Parameters for -2 Speed Grade Devices

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All APEX 20K devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1-1990 specification. JTAG boundary-scan testing can be performed before or after configuration, but not during configuration. APEX 20K devices can also use the JTAG port for configuration with the Quartus II software or with hardware using either Jam Files (.jam) or Jam Byte-Code Files (.jbc). Finally, APEX 20K devices use the JTAG port to monitor the logic operation of the device with the SignalTap embedded logic analyzer. APEX 20K devices support the JTAG instructions shown in Table 19. Although EP20K1500E devices support the JTAG BYPASS and SignalTap instructions, they do not support boundary-scan testing or the use of the JTAG port for configuration.

Table 19. APEX 20K JT	Table 19. APEX ZUK JTAG Instructions									
JTAG Instruction	Description									
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern to be output at the device pins. Also used by the SignalTap embedded logic analyzer.									
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.									
BYPASS (1)	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation.									
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE to be serially shifted out of TDO .									
IDCODE	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.									
ICR Instructions	Used when configuring an APEX 20K device via the JTAG port with a MasterBlaster TM or ByteBlasterMV TM download cable, or when using a Jam File or Jam Byte-Code File via an embedded processor.									
SignalTap Instructions (1)	Monitors internal device operation with the SignalTap embedded logic analyzer.									

Note to Table 19:

(1) The EP20K1500E device supports the JTAG BYPASS instruction and the SignalTap instructions.

All specifications are always representative of worst-case supply voltage and junction temperature conditions. All output-pin-timing specifications are reported for maximum driver strength.

Figure 36 shows the f_{MAX} timing model for APEX 20K devices.



Figure 37 shows the f_{MAX} timing model for APEX 20KE devices. These parameters can be used to estimate f_{MAX} for multiple levels of logic. Quartus II software timing analysis should be used for more accurate timing information.

Tables 40 through 42 show the f_{MAX} timing parameters for EP20K100, EP20K200, and EP20K400 APEX 20K devices.

Symbol	-1 Snee	-1 Sneed Grade		d Grade	-3 Sner	Units	
oymbol			2 0000		0 0000	_	
	Min	Max	Min	Max	Min	Max	
t _{SU}	0.5		0.6		0.8		ns
t _H	0.7		0.8		1.0		ns
t _{CO}		0.3		0.4		0.5	ns
t _{LUT}		0.8		1.0		1.3	ns
t _{ESBRC}		1.7		2.1		2.4	ns
t _{ESBWC}		5.7		6.9		8.1	ns
t _{ESBWESU}	3.3		3.9		4.6		ns
t _{ESBDATASU}	2.2		2.7		3.1		ns
t _{ESBDATAH}	0.6		0.8		0.9		ns
t _{ESBADDRSU}	2.4		2.9		3.3		ns
t _{ESBDATACO1}		1.3		1.6		1.8	ns
t _{ESBDATACO2}		2.6		3.1		3.6	ns
t _{ESBDD}		2.5		3.3		3.6	ns
t _{PD}		2.5		3.0		3.6	ns
t _{PTERMSU}	2.3		2.6		3.2		ns
t _{PTERMCO}		1.5		1.8		2.1	ns
t _{F1-4}		0.5		0.6		0.7	ns
t _{F5-20}		1.6		1.7		1.8	ns
t _{F20+}		2.2		2.2		2.3	ns
t _{CH}	2.0		2.5		3.0		ns
t _{CL}	2.0		2.5		3.0		ns
t _{CLRP}	0.3		0.4		0.4		ns
t _{PREP}	0.5		0.5		0.5		ns
t _{ESBCH}	2.0		2.5		3.0		ns
t _{ESBCL}	2.0		2.5		3.0		ns
t _{ESBWP}	1.6		1.9		2.2		ns
t _{ESBRP}	1.0		1.3		1.4		ns

Table 60. EP20K60E External Bidirectional Timing Parameters											
Symbol	-	1	-:	2	-	Unit					
	Min	Max	Min	Max	Min	Max					
t _{insubidir}	2.77		2.91		3.11		ns				
t _{inhbidir}	0.00		0.00		0.00		ns				
t _{outcobidir}	2.00	4.84	2.00	5.31	2.00	5.81	ns				
t _{xzbidir}		6.47		7.44		8.65	ns				
t _{zxbidir}		6.47		7.44		8.65	ns				
t _{insubidirpll}	3.44		3.24		-		ns				
t _{inhbidirpll}	0.00		0.00		-		ns				
t _{outcobidirpll}	0.50	3.37	0.50	3.69	-	-	ns				
t _{XZBIDIRPLL}		5.00		5.82		-	ns				
t _{ZXBIDIRPLL}		5.00		5.82		-	ns				

Tables 61 through 66 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K100E APEX 20KE devices.

Table 61. EP20K100E f _{MAX} LE Timing Microparameters											
Symbol	Symbol -1			-2		3	Unit				
	Min	Max	Min	Max	Min	Max					
t _{SU}	0.25		0.25		0.25		ns				
t _H	0.25		0.25		0.25		ns				
t _{CO}		0.28		0.28		0.34	ns				
t _{LUT}		0.80		0.95		1.13	ns				

Table 74. EP20k	(200E f _{MAX} ESI	3 Timing Micr	oparameters				
Symbol	-	1		-2	-	-3	
	Min	Мах	Min	Мах	Min	Max	
t _{ESBARC}		1.68		2.06		2.24	ns
t _{ESBSRC}		2.27		2.77		3.18	ns
t _{ESBAWC}		3.10		3.86		4.50	ns
t _{ESBSWC}		2.90		3.67		4.21	ns
t _{ESBWASU}	0.55		0.67		0.74		ns
t _{ESBWAH}	0.36		0.46		0.48		ns
t _{ESBWDSU}	0.69		0.83		0.95		ns
t _{ESBWDH}	0.36		0.46		0.48		ns
t _{ESBRASU}	1.61		1.90		2.09		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.42		1.71		2.01		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.06		-0.07		0.05		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.13		0.31		ns
t _{ESBRADDRSU}	0.18		0.23		0.39		ns
t _{ESBDATACO1}		1.09		1.35		1.51	ns
t _{ESBDATACO2}		2.19		2.75		3.22	ns
t _{ESBDD}		2.75		3.41		4.03	ns
t _{PD}		1.58		1.97		2.33	ns
t _{PTERMSU}	1.00		1.22		1.51		ns
t _{PTERMCO}		1.10		1.37		1.09	ns

Table 75. EP20K200E f _{MAX} Routing Delays											
Symbol	-1			-2	-:	3	Unit				
	Min	Max	Min	Max	Min	Max					
t _{F1-4}		0.25		0.27		0.29	ns				
t _{F5-20}		1.02		1.20		1.41	ns				
t _{F20+}		1.99		2.23		2.53	ns				

Table 76. EP20K200E Minimum Pulse Width Timing Parameters											
Symbol		1	-	-2			Unit				
	Min	Max	Min	Max	Min	Max					
t _{CH}	1.36		2.44		2.65		ns				
t _{CL}	1.36		2.44		2.65		ns				
t _{CLRP}	0.18		0.19		0.21		ns				
t _{PREP}	0.18		0.19		0.21		ns				
t _{ESBCH}	1.36		2.44		2.65		ns				
t _{ESBCL}	1.36		2.44		2.65		ns				
t _{ESBWP}	1.18		1.48		1.76		ns				
t _{ESBRP}	0.95		1.17		1.41		ns				

Table 77. EP20K200E External Timing Parameters											
Symbol	-	-1		-2		-3					
	Min	Max	Min	Max	Min	Max					
t _{INSU}	2.24		2.35		2.47		ns				
t _{INH}	0.00		0.00		0.00		ns				
t _{outco}	2.00	5.12	2.00	5.62	2.00	6.11	ns				
t _{INSUPLL}	2.13		2.07		-		ns				
t _{INHPLL}	0.00		0.00		-		ns				
t _{outcopll}	0.50	3.01	0.50	3.36	-	-	ns				

Tables 85 through 90 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K400E APEX 20KE devices.

Table 85. EP20K400E f _{MAX} LE Timing Microparameters									
Symbol	Symbol -1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit		
	Min	Max	Min	Max	Min	Max			
t _{SU}	0.23		0.23		0.23		ns		
t _H	0.23		0.23		0.23		ns		
t _{CO}		0.25		0.29		0.32	ns		
t _{LUT}		0.70		0.83		1.01	ns		

Table 94. EP20K600E Minimum Pulse Width Timing Parameters								
Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit	
	Min	Max	Min	Max	Min	Max		
t _{CH}	2.00		2.50		2.75		ns	
t _{CL}	2.00		2.50		2.75		ns	
t _{CLRP}	0.18		0.26		0.34		ns	
t _{PREP}	0.18		0.26		0.34		ns	
t _{ESBCH}	2.00		2.50		2.75		ns	
t _{ESBCL}	2.00		2.50		2.75		ns	
t _{ESBWP}	1.17		1.68		2.18		ns	
t _{ESBRP}	0.95		1.35		1.76		ns	

Table 95. EP20K600E External Timing Parameters									
Symbol -1 Speed Grade		d Grade	-2 Speed Grade		-3 Speed Grade		Unit		
	Min	Max	Min	Max	Min	Max			
t _{INSU}	2.74		2.74		2.87		ns		
t _{INH}	0.00		0.00		0.00		ns		
t _{outco}	2.00	5.51	2.00	6.06	2.00	6.61	ns		
tINSUPLL	1.86		1.96		-		ns		
t _{INHPLL}	0.00		0.00		-		ns		
toutcopll	0.50	2.62	0.50	2.91	-	-	ns		

Table 96. EP20K600E External Bidirectional Timing Parameters								
Symbol	-1 Speed Grade		-2 Spee	d Grade	-3 Speed Grade		Unit	
	Min	Max	Min	Мах	Min	Max		
t _{insubidir}	0.64		0.98		1.08		ns	
t _{inhbidir}	0.00		0.00		0.00		ns	
t _{outcobidir}	2.00	5.51	2.00	6.06	2.00	6.61	ns	
t _{XZBIDIR}		6.10		6.74		7.10	ns	
t _{ZXBIDIR}		6.10		6.74		7.10	ns	
t _{insubidirpll}	2.26		2.68		-		ns	
t _{inhbidirpll}	0.00		0.00		-		ns	
t _{outcobidirpll}	0.50	2.62	0.50	2.91	-	-	ns	
t _{XZBIDIRPLL}		3.21		3.59		-	ns	
t _{ZXBIDIRPLL}		3.21		3.59		-	ns	

Revision History

The information contained in the *APEX 20K Programmable Logic Device Family Data Sheet* version 5.1 supersedes information published in previous versions.

Version 5.1

APEX 20K Programmable Logic Device Family Data Sheet version 5.1 contains the following changes:

- In version 5.0, the VI input voltage spec was updated in Table 28 on page 63.
- In version 5.0, *Note* (5) to Tables 27 through 30 was revised.
- Added *Note* (2) to Figure 21 on page 33.

Version 5.0

APEX 20K Programmable Logic Device Family Data Sheet version 5.0 contains the following changes:

- Updated Tables 23 through 26. Removed 2.5-V operating condition tables because all APEX 20K devices are now 5.0-V tolerant.
- Updated conditions in Tables 33, 38 and 39.
- Updated data for t_{ESBDATAH} parameter.

Version 4.3

APEX 20K Programmable Logic Device Family Data Sheet version 4.3 contains the following changes:

- Updated Figure 20.
- Updated *Note* (2) to Table 13.
- Updated notes to Tables 27 through 30.

Version 4.2

APEX 20K Programmable Logic Device Family Data Sheet version 4.2 contains the following changes:

- Updated Figure 29.
- Updated *Note* (1) to Figure 29.